



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	ISC031N10NM6	<b>Issued</b>	08. February 2022
<b>MA#</b>	MA005428256		
<b>Package</b>	PG-TDSON-8-36	<b>Weight*</b>	116.68 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.010	1.72	1.72	17227	17227
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		126	
	non noble metal	iron	7439-89-6	0.049	0.04		419	
	non noble metal	copper	7440-50-8	48.769	41.82	41.87	417981	418526
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	385	385
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		695	
	plastics	epoxy resin	-	6.410	5.49		54939	
	inorganic material	silicondioxide	60676-86-0	34.080	29.21	34.77	292083	347717
leadfinish	non noble metal	tin	7440-31-5	1.392	1.19	1.19	11926	11926
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1661	1661
solder	non noble metal	tin	7440-31-5	0.049	0.04		419	
	noble metal	silver	7440-22-4	0.061	0.05		524	
	non noble metal	lead	7439-92-1	2.336	2.00	2.09	20021	20964
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			44	
	non noble metal	iron	7439-89-6	0.017	0.01		147	
	non noble metal	copper	7440-50-8	17.131	14.68	14.69	146826	147017
clip plating	noble metal	silver	7440-22-4	1.059	0.91	0.91	9077	9077
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.55	2.55	25466	25500
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com